

SOT352-1

plastic rectangular-bent single in-line medium power package with fin; 9 leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	RBS9MPF
Package type industry code	RBS9MPF
Package style descriptive code	RBS (right-angle bent single in-line)
Package style suffix code	MPF (medium power; with fin)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	12-3-2003

Table 1. Package summary

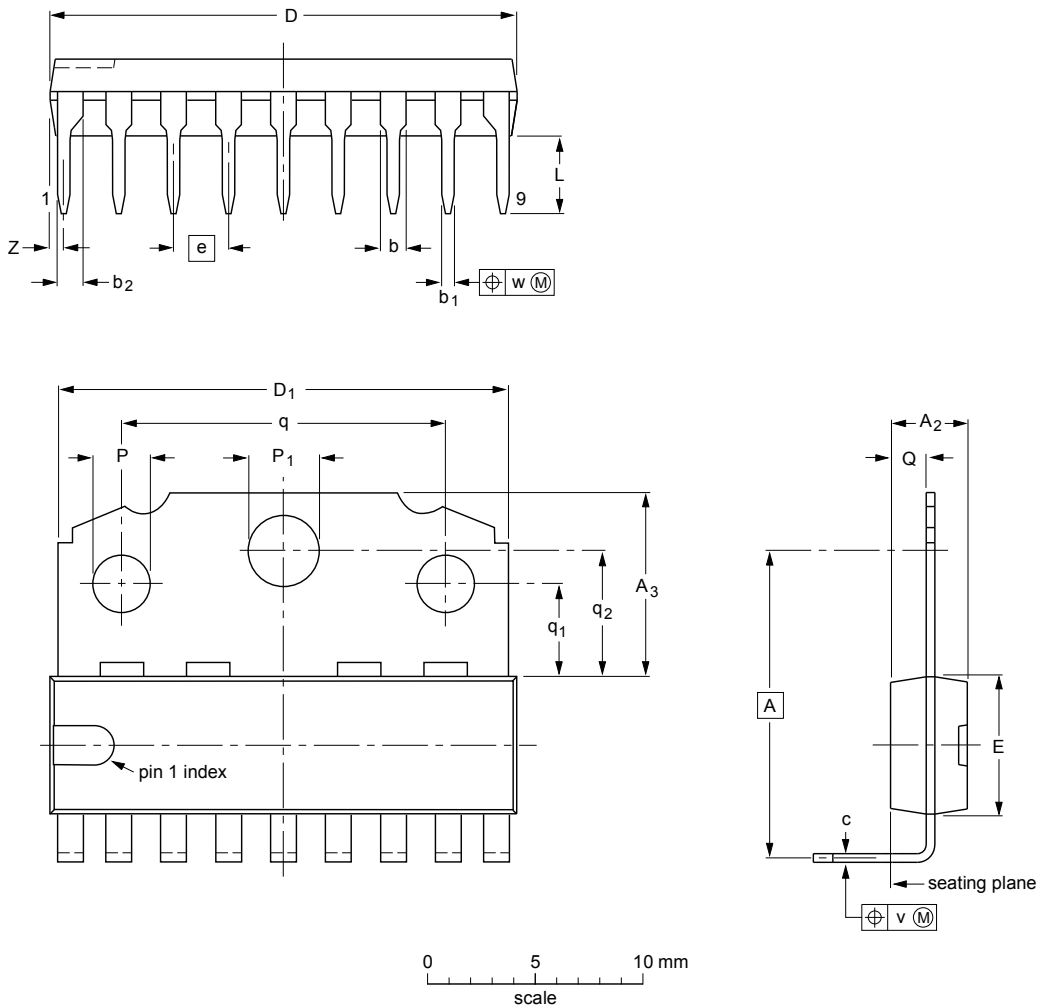
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	21.4	-	21.6	21.8	mm
E	package width	6.2	-	6.35	6.48	mm
A ₂	package height	[tbd]	-	3.55	3.7	mm
n ₂	actual quantity of termination	-	-	9	-	



2. Package outline

RBS9MPF: plastic rectangular-bent single in-line medium power package with fin; 9 leads

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾	A ₂ max.	A ₃	b	b ₁	b ₂	c	D ⁽²⁾	D ₁	E ⁽²⁾	e	L	P	P ₁	Q	q	q ₁	q ₂	v	w	Z ⁽²⁾ max.
mm	14.45 13.95	3.7	8.7 8.0	1.40 1.14	0.67 0.50	1.40 1.14	0.48 0.38	21.8 21.4	21.4 20.7	6.48 6.20	2.54	3.8 3.3	2.75 2.50	3.4 3.2	1.75 1.55	15.1 14.9	4.4 4.2	5.9 5.7	0.6	0.25	1

Notes

1. Dimension is specified at seating plane.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT352-1						97-12-16 03-03-12

Fig. 1. Package outline RBS9MPF (SOT352-1)

3. Legal information

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